Power Inductor

UHP252012NF-SERIES

		ECN HISTORY LIS	ST		
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	13/04/02	新 發 行	楊祥忠	詹偉特	林宜蕰
1.1	14/03/12	1 修改 B 尺寸從 2.0 -0.05/+0.35 改為 2.0 -0.1/+0.2 2 修改第 6 項可靠度 3 修改 7-2 內容 L.H 尺寸	楊祥忠	詹偉特	林宜蕰
備					
註					

Power Inductor

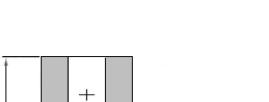
UHP252012NF-SERIES

1. Features

- 1. This specification applies Low Profile Power Inductors.
- 2. 100% Lead(Pb) & Halogen-Free and RoHS compliant.

В

2. Dimension





D

Ε

D

Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
UHP252012NF	2.5 -0.1/+0.2	2.0 -0.1/+0.2	1.2 max.	0.85 ref.	0.80 ref.

Units: mm

3. Part Numbering

 UHP
 252012
 NF
 4R7
 M

 A
 B
 C
 D
 E

A: Series

B: Dimension

C: Lead Free Material
D: Inductance 4R7=4.7uH

E: Inductance Tolerance M=±20% Y=±30%

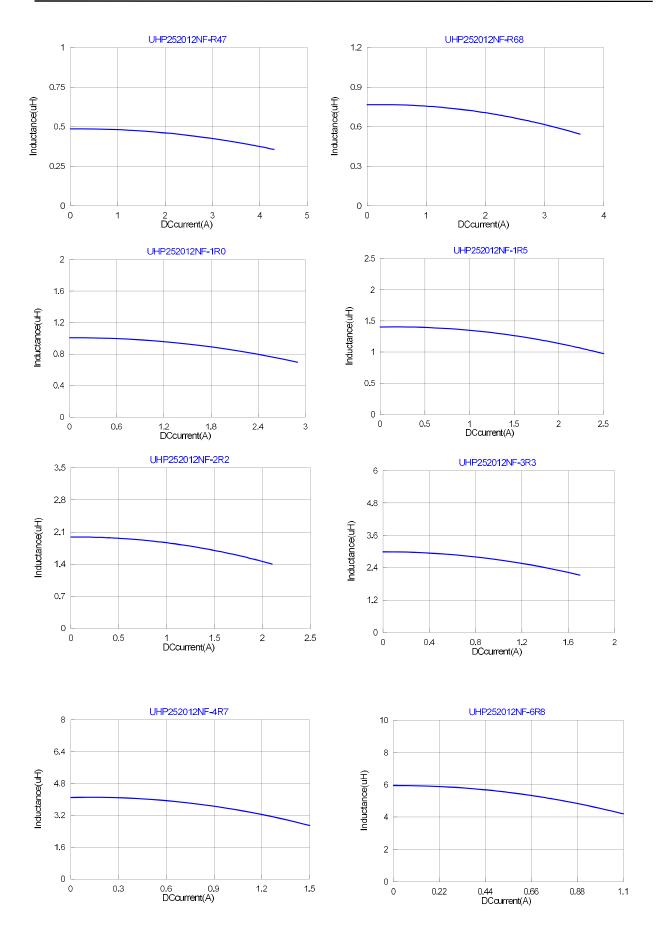
4. Specification

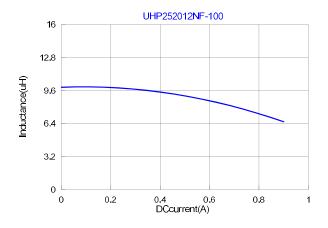
TAI-TECH Part Number	Inductance (uH)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) ±20%	I sat (A) typ.	I sat (A) Max.	I rms (A) typ	I rms (A) Max.
UHP252012NF-R47M	0.47	±20%	0.1V/1M	0.028	4.00	3.60	3.70	3.35
UHP252012NF-R68M	0.68	±20%	0.1V/1M	0.036	3.00	2.70	3.30	3.00
UHP252012NF-1R0M	1.0	±20%	0.1V/1M	0.049	2.70	2.45	2.60	2.30
UHP252012NF-1R5M	1.5	±2 0 %	0.1V/1M	0.063	2.30	2.05	2.20	1.95
UHP252012NF-2R2M	2.2	±20%	0.1V/1M	0.080	2.15	1.95	1.85	1.65
UHP252012NF-3R3M	3.3	±20%	0.1V/1M	0.120	1.70	1.50	1.45	1.30
UHP252012NF-4R7M	4.7	±20%	0.1V/1M	0.176	1.50	1.35	1.20	1.05
UHP252012NF-6R8M	6.8	±20%	0.1V/1M	0.250	1.15	1.00	1.00	0.90
UHP252012NF-100M	10	±20%	0.1V/1M	0.410	0.85	0.75	0.75	0.65
UHP252012NF-150M	15	±20%	0.1V/1M	0.540	0.63	0.56	0.60	0.54
UHP252012NF-220M	22	±20%	0.1V/1M	0.850	0.56	0.50	0.50	0.45

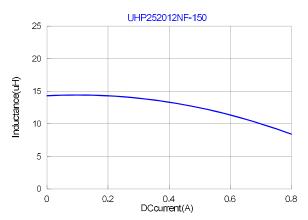
Note:

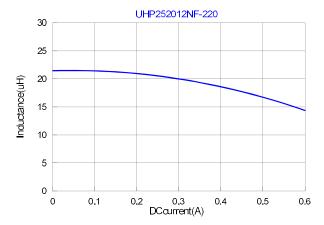
Isat : Based on inductance change $\ (\triangle L/L0: \leq -30\%) \ @$ ambient temp. 25%

Irms : Based on temperature rise $(\triangle T : 40^{\circ}C.)$ Max



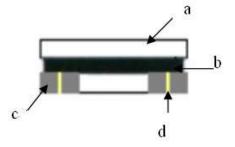


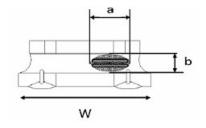




5. Material List

No.	Description	Specification
a.	Core	Ferrite Core
b.	Coating	Epoxy with magnetic powder
С	Termination	Tin Pb Free
d	Wire	Enameled Copper Wire





Exposed wire tolerance limit of coating resin part on product side. Size of exposed wire occurring to coating resin is specified below.

- 1. Width direction (dimension a): Acceptable when a \leq w/2 Nonconforming when a > w/2
- 2. Length direction (dimension b): Dimension b is not specified.
- 3. The total area of exposed wire occurring to each sides is not greater than 50% of coating resin area, and is acceptable.

6. Reliability and Test Condition

Temperature Rise Test ΔT 40°C Max Temperature Rise Test ΔT 40°C Max Applied the allov 2. Temperature me Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value RDC : within±15% of initial value and shall not exceed the specification value 200±5 (coder temp)	rrent (Isat) will cause L0 ately \triangle L(%). ent (Irms) will cause the coil temperature rise $T(^{\circ}C)$ without core loss.				
Inductance L Agilent-4291, Agik DC Resistance Agilent-4291, Agik Rated Current Base on temp. rise & △L/L0A≤30%. Saturation DC Current to drop approximately △1 1.Applied the allow 2. Temperature Rise Test Temperature Rise Test △T 40℃ Max 40℃ Max Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value RDC : within±10% of initial value and shall not exceed the specification value Temperature (°C)	rrent (Isat) will cause L0 ately <u>L(%).</u> ent (Irms) will cause the coil temperature rise T(°C) without core loss. wed DC current.				
Refer to standard electrical characteristic list DC Resistance Base on temp. rise & △L/L0A≦30%. Saturation DC Cur to drop approximately △T 1.Applied the allov 2.Temperature me Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value RDC : within±15% of initial value and shall not exceed the specification value Temperature Temperature Temperature	rrent (Isat) will cause L0 ately <u>L(%).</u> ent (Irms) will cause the coil temperature rise T(°C) without core loss. wed DC current.				
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DC Resistance Agilent-4338 Rated Current Base on temp. rise & △L/L0A ≤ 30%. Saturation DC Cur to drop approximately to drop approximately △T 1.Applied the allow 2.Temperature me Temperature Rise Test ΔT 40°C Max 1.Applied the allow 2.Temperature me Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value Temperature (°C) Solder Heat Resistance RDC : within±15% of initial value and shall not exceed the specification value Temperature (°C)	ately $\triangle L$ (%). ent (Irms) will cause the coil temperature rise $T(^{\circ}C)$ without core loss. wed DC current.				
Rated Current Base on temp. rise & △L/L0A≦30%. Saturation DC Curto drop approximately to drop approximately △T 1.Applied the allow 2.Temperature me Temperature Rise Test ΔT 40°C Max Heat Rated Curre approximately △T 1.Applied the allow 2.Temperature me Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value Solder Heat Resistance Appearance : No damage. Temperature (°C) RDC : within±15% of initial value and shall not exceed the specification value Temperature (°C)	ately $\triangle L(\%)$. ent (Irms) will cause the coil temperature rise $T({}^{\circ}C)$ without core loss. wed DC current.				
Temperature Rise Test ΔT 40°C Max Applied the allov 2. Temperature me Mechanical Performance Test Appearance : No damage. Inductance : within±10% of initial value RDC : within±15% of initial value and shall not exceed the specification value 200±5 (colder temp) to drop approximate to drop approximately Δ1 1.Applied the allov 2. Temperature me	ately $\triangle L$ (%). ent (Irms) will cause the coil temperature rise $T(^{\circ}C)$ without core loss. wed DC current.				
Temperature Rise Test ΔT 40°C Max Heat Rated Curre approximately Δ1 1.Applied the allow 2.Temperature me Wechanical Performance Test Appearance: No damage. Inductance: within±10% of initial value RDC: within±15% of initial value and shall not exceed the specification value Temperature (°C) 280±5 (colder temp)	ent (Irms) will cause the coil temperature rise $T(^\circ\!\!\!\!\!^\circ)$ without core loss. wed DC current.				
Appearance: No damage. Inductance: within±15% of initial value and shall not exceed the specification value Temperature	wed DC current.				
Appearance: No damage. Inductance: within±10% of initial value RDC: within±15% of initial value and shall not exceed the specification value Temperature (°C) 280±5 (solder temps)					
Solder Heat Resistance Inductance: within±10% of initial value RDC: within±15% of initial value and shall not exceed the specification value 280±5 (solder temp)					
Solder Heat Resistance Inductance: within±10% of initial value RDC: within±15% of initial value and shall not exceed the specification value 280±5 (solder temp)					
Solder Heat Resistance RDC: within ±15% of initial value and shall not exceed the specification value 200±5 (solder temp)	Toppospoli iro				
(solder temp)	Time ramplimmersion (s) Temperature ramplimmersion and emersion rate Number of heat cycles				
	10±1 25mm/s±6 mm/s 1				
Depth: completely	cover the termination				
Solder: Sn99.5%- Temperature: 245:	Preheat: 150°C, 60sec. « Solder: Sn99.5%-Cu0. 5% « Temperature: 245±5°C « Flux for lead free: Rosin. 9.5% «				
Solderability Test More than 95% of terminal electrode should be covered with solder. Dip time: 4±1sec	۰				
Depth; completely	over the termination				
Reliability Test					
Preconditioning:Run	n through IR reflow for 2 times.(IPC/JEDEC fication Reflow Profiles				
Temperature: 125±					
Life Test Temperature: 85±	-2°C(Inductor)				
Applied current: ra	Applied current: rated current				
	Duration: 1000±12hrs				
Preconditioning: Rui	emperature after placing for 24±2 hrs n through IR reflow for 2 times.(IPC/JEDEC fication Reflow Profiles				
Step1:-40±2°C 30.	Step1: -40±2°C 30±5min				
	Step2: 25±2°C ≤0.5min				
Thermal shock Appearance: No damage. Step3: 105±2°C 30)±5min				
Inductance: within±10% of initial value Number of cycles:	500 emprature after placing for 24±2 hrs				
RDC: within ±15% of initial value and shall not exceed the specification value	emplature and placing for 24±2 ms				
Preconditioning: Rur J-STD-020DC lassif	n through IR reflow for 2 times.(IPC/JEDEC Fication Reflow Profiles				
Humidity Resistance Test Humidity: 85±2% I					
Temperature: 85°C	±2°C				
	Min. with 100% rated current				
Preconditioning:Run	amparatura after placing for 24.2				
Vibration Test Oscillation Freque	emperature after placing for 24±2 hrs n through IR reflow for 2 times.(IPC/JEDEC				
Equipment: Vilor Total Amplitude:1.	n through IR reflow for 2 times.(IPC/JEDEC fication Reflow Profiles ency: 10~2K~10Hz for 20 minutes				
Testing Time: 1 orientations) •	n through IR reflow for 2 times.(IPC/JEDEC ication Reflow Profiles nory: 10-2K-10Hz for 20 minutes ration checker				

7. Soldering and Mounting

7-1. Soldering

Mildly activated rosin fluxes are preferred. TAI-TECH terminations are suitable for all wave and re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

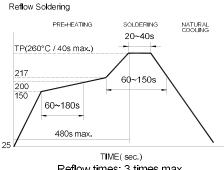
7-1.1 Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

7-1.2 Soldering Iron(Figure 2):

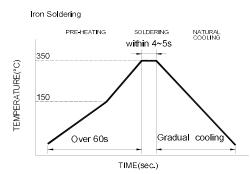
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150°C
 355°C tip temperature (max)
- Never contact the ceramic with the iron tip
- · Use a 20 watt soldering iron with tip diameter of 1.0mm
- x) 1.0mm tip diameter (max) Limit soldering time to 4~5 sec.



Reflow times: 3 times max.

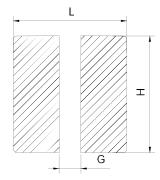
Fig.1



Iron Soldering times: 1 times max.

Fig 2

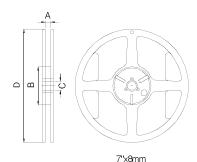
7-2. Recommended PC Board Pattern



L(mm)	G(mm)	H(mm)
2.6	0.8	2.1

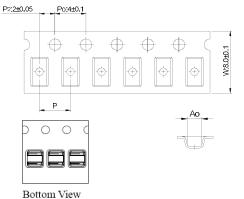
8. Packaging Information

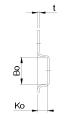
8-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
7"x8mm	8.4±1.0	50 min.	13±0.8	178±2

8-2. Tape Dimension / 8mm



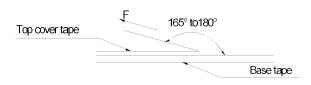


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
UHP	252012	2.85±0.1	2.45±0.1	1.40±0.1	4.0±0.1	0.23±0.05

8-3. Packaging Quantity

Chip size	252012
Chip / Reel	2000

8-4. Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp.	mp. Room Humidity Room atm		Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

- Storage Conditions
- To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



號碼(No.) : CE/2013/C5949 日期(Date) : 2014/01/07 頁數(Page) : 1 of 12

Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(東莞臺慶精密電子有限公司 / TAI-TECH ADVANCED ELECTRONICS (DONGGUAN) CO. LTD.)

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(耀鑽科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

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(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(桃園縣中壢市中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN (R. O. C.))

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

: SMD POWER INDUCTOR

樣品型號(Style/Item No.)

: HPC, MDC, FPC, FWP, SPC, SPI, UHP, DFP, TLPC, TLPH, TLI SERIES

收件日期(Sample Receiving Date)

: 2013/12/30

測試期間(Testing Period)

: 2013/12/30 TO 2014/01/07

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).



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號碼(No.): CE/2013/C5949 日期(Date): 2014/01/07 頁數(Page): 2 of 12

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測試結果(Test Results)

測試部位(PART NAME)No.1 : 整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鎬 / Cadmium (Cd)	mg/kg	参考IEC 62321-5: 2013方法,以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5: 2013 and performed by ICP-AES.	2	n.d.
鉛 / Lead (Pb)	mg/kg	参考IEC 62321-5: 2013方法,以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5: 2013 and performed by ICP-AES.	2	n.d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4: 2013方法, 以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4: 2013 and performed by ICP-AES.	2	n.d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	参考IEC 62321: 2008方法,以UV-VIS檢測. / With reference to IEC 62321: 2008 and performed by UV-VIS.	2	n.d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鄰苯二甲酸甲苯基丁酯 / BBP (Benzyl butyl phthalate) (CAS No.: 85-68-7)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.003	n.d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.003	n.d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761-40-0; 68515-49-1)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.01	n.d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553-12-0; 68515-48-0)	. %	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.01	n.d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.003	n.d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.003	n.d.
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84- 69-5)	%	參考EN 14372, 以氣相層析/質譜儀檢測之. / With reference to EN 14372. Analysis was performed by GC/MS.	0.003	n.d.

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Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(東莞臺慶精密電子有限公司 / TAI-TECH ADVANCED ELECTRONICS (DONGGUAN) CO. LTD.)

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桃園縣楊梅市幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI CITY, TAO-YUAN HSIEN. TAIWAN R. O. C.

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(桃園縣中壢市中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN (R. O. C.))

測試項目 (Test Items) 六溴環十二烷及所有主要被辨别出的 異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α-HBCDD), β-HBCDD, γ-HBCDD) (CAS) No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	單位 (Unit) mg/kg	測試方法 (Method) 参考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 method. Analysis was performed by GC/MS.	方法偵測 極限値 (MDL) 5	結果 (Result) No.1 n.d.
多溴聯苯總和 / Sum of PBBs	mg/kg	參考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS.	-	n.d.
一溴聯苯 / Monobromobiphenyl	mg/kg		5	<u> </u>
二溴聯苯 / Dibromobiphenyl	mg/kg		5	n.d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n.d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n.d.
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n.d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n.d.
七溴聯苯 / Heptabromobiphenyl	mg/kg		5	n.d.
へ 決 聯 苯 / Octabromobi phenyl	mg/kg		5	n.d.
九溴聯苯 / Nonabromobiphenyl	mg/kg		5	n.d.
十溴聯苯 / Decabromobiphenyl	mg/kg		5	n.d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	参考IEC 62321: 2008方法,以氣相層析/質 譜儀檢測. / With reference to IEC 62321: 2008 and performed by GC/MS.	-	n.d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n.d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n.d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg		5	n.d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n.d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n.d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n.d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n.d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n.d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n.d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n.d.
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg	参考BS EN 14582:2007, 以離子層析儀分析. / With reference to BS EN 14582:2007. Analysis was performed by IC.	50	n.d.
鹵素(氣)/ Halogen-Chlorine (Cl) (CAS No.: 22537-15-1)	mg/kg		50	n.d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg		50	n.d.
鹵素(碘)/ Halogen-Iodine(I) (CAS No.: 14362-44-8)	mg/kg		50	n.d.

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備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個别單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

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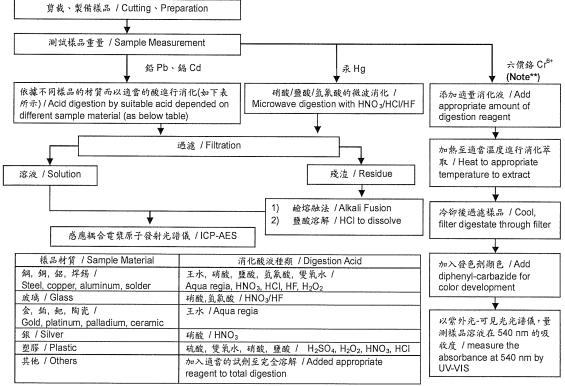
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- 1) 根據以下的流程圖之條件,樣品己完全溶解。(六價络測試方法除外) / These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)
- 2) 测试人員:楊登偉 / Name of the person who made measurement: Climbgreat Yang
- 3) 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



Note** (For IEC 62321)

- (1) 針對非金屬材料加入鹼性消化液,加熱至 90~95℃萃取. / For non-metallic material, add alkaline digestion reagent and heat to 90~95 ℃.
- (2) 針對金屬材料加入純水,加熱至沸騰萃取. / For metallic material, add pure water and heat to boiling.

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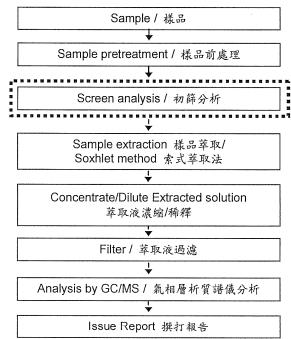
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多溴聯苯/多溴聯苯醚分析流程圖 / PBB/PBDE analytical FLOW CHART

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang

初次測試程序 / First testing process ———

確認程序 / Confirmation process - · - ·▶



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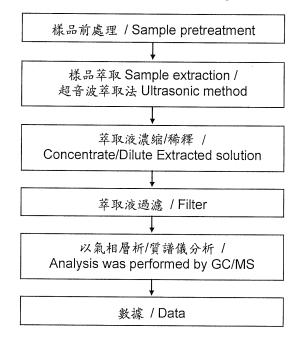
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六溴環十二烷分析流程圖 / HBCDD analytical flow chart

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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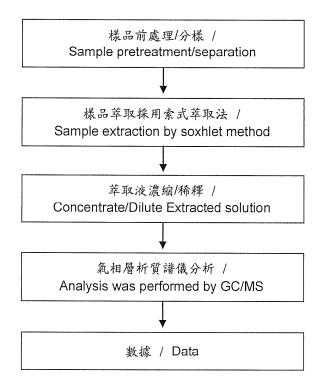
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可塑劑分析流程圖 / Analytical flow chart of phthalate content

- 測試人員:翁賜彬 / Name of the person who made measurement: Roman Wong
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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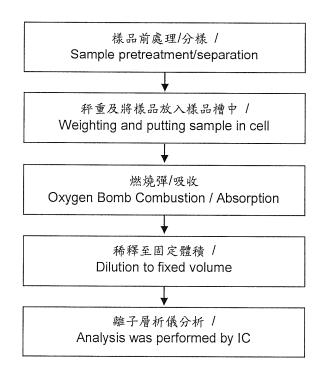
(廣東省東莞市黄江鎮黄牛埔福祥街2號 / NO. 2, FUXIANG STREET, HUANGNIUPU, HUANGJIANG TOWN, DONGGUAN, GUANGDONG)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU,

(桃園縣中壢市中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI CITY, TAOYUAN COUNTY 320, TAIWAN (R. O. C.))

鹵素分析流程圖 / Analytical flow chart of halogen content

- 測試人員:陳恩臻 / Name of the person who made measurement: Rita Chen
- 測試負責人:張啓興 / Name of the person in charge of measurement: Troy Chang



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號碼(No.) : CE/2013/C5949 日期(Date) : 2014/01/07 頁數(Page) : 12 of 12

Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(東莞臺慶精密電子有限公司 / TAI-TECH ADVANCED ELECTRONICS (DONGGUAN) CO. LTD.)

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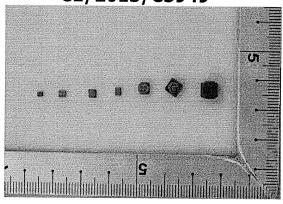
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

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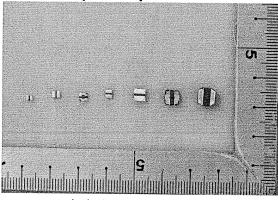
* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2013/C5949



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** 報告結尾 (End of Report) **

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